







# PCN21002: Implement Microchip Label and Packing Changes for Microsemi FPGA and MSA (HiRel) Products

January 22, 2021

## Description

Details	Pre Change	Post Change
Label for bag/reel		
Label on inner carton		
Labels on black conductive boxes	Label with Microsemi name	Label with Microchip name (no change in other information, just the name change)
Cartons (inner and outer)	Cardboard boxes (of various shapes and sizes to ship product in tape/reel, tubes, trays, and black boxes)	Cardboard boxes with Microchip logo (of various shapes and sizes to ship product in tape/reel, tubes, trays, and black boxes)
Labels on outer carton		
Tray strapping	2 width tray straps/band	3 width straps/bands and 1 length strap/band
Cartons (inner and outer)	Cardboard boxes (of various shapes and sizes to ship product in tape/reel, tubes, trays, and black boxes)	Cardboard boxes with Microchip logo (of various shapes and sizes to ship product in tape/reel, tubes, trays, and black boxes)
Logo and address on documents accompanying product (example: C of C, packing list, and so on)	Microsemi logo with address	Microsemi logo with address

**Reason for Change**

Streamlining internal processing by standardizing the packing method as part of the integration of Microsemi to Microchip processes.

**Application Impact**

There is no impact on form, fit, function, quality, or reliability.

**Method of Identifying Changed Product**

The above mentioned change scheme allows for the best identification platform.

**Products Affected by Change**

See document with list of affected part numbers accompanying this customer notification (PCN21002\_FPGA\_MSA\_Affected\_Part\_Numbers).

**Production Shipment Schedule**

Product with the updated labeling scheme is planned to be shipped no sooner than February 25, 2021.

During the transition period (February/March 2021), customers may see shipments with either labeling/packing schemes while any existing inventory of parts is depleted.

**Qualification Data**

Not applicable, as this is not a product-related change.

**Samples Availability**

Not applicable.

**Contact Information**

If you have any questions about this subject, contact Microsemi Technical Support department by using the support portal at <https://soc.microsemi.com/Portal/Default.aspx>

**Regards,**

Microsemi Corporation

Any projected dates in this notification are based on the most current product information at the time this notification is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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